



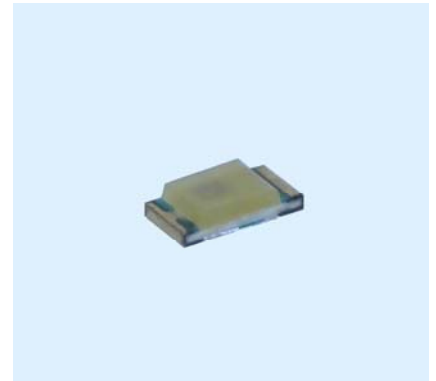
Technical Data Sheet

0603 Package Chip LED (0.3mm Height)

19-218UWD/S327/TR8

Features

- Package in 8mm tape on 7" diameter reel.
- Compatible with automatic placement equipment.
- Compatible with infrared and vapor phase reflow solder process.
- Mono-color type.
- Pb-free.
- The product itself will remain within RoHS compliant version.



Descriptions

- The 19-218 SMD Taping is much smaller than lead frame type components, thus enable smaller board size, higher packing density, reduced storage space and finally smaller equipment to be obtained.
- Besides, lightweight makes them ideal for miniature applications. etc.

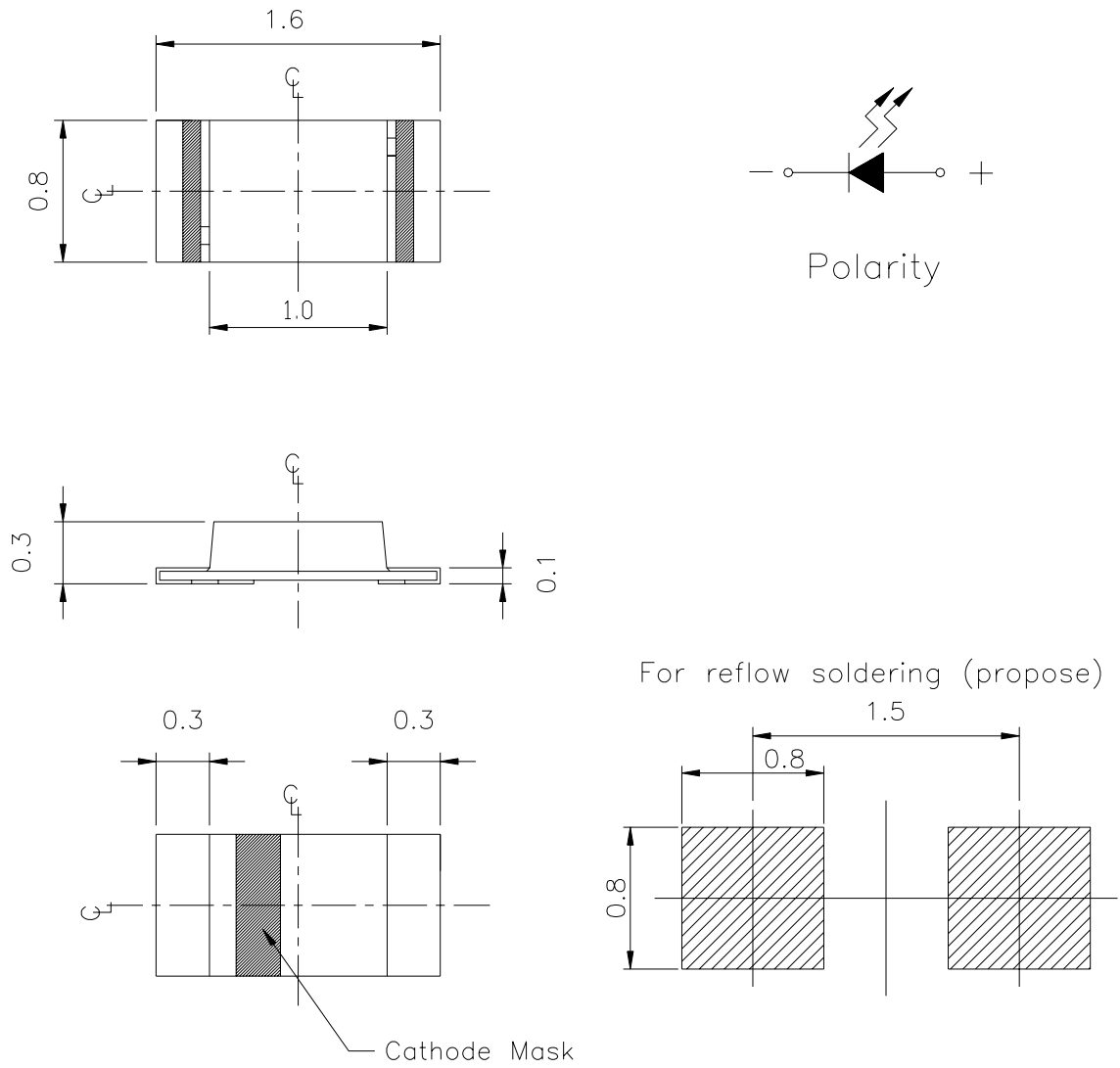
Applications

- Automotive: backlighting in dashboard and switch.
- Telecommunication: indicator and backlighting in telephone and fax.
- Flat backlight for LCD, switch and symbol.
- General use.

Device Selection Guide

Part No.	Chip	Emitted Color	Lens Color
	Material		
19-218UWD/S327/TR8	InGaN	Pure White	Yellow Diffused

Package Outline Dimensions



Note: The tolerances unless mentioned is $\pm 0.1\text{mm}$,Unit = mm

Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Rating	Unit
Reverse Voltage	V _R	5	V
Forward Current	I _F	25	mA
Operating Temperature	T _{opr}	-40 ~ +85	°C
Storage Temperature	T _{stg}	-40 ~ +90	°C
Soldering Temperature	T _{sol}	260 (for 5 seconds)	°C
Electrostatic Discharge	ESD	150	V
Power Dissipation	P _d	110	mW
Peak Forward Current (Duty 1/10 @1KHz)	I _F	100	mA

Notes:

*We only guarantee the ESD <2000V after customer to process.

Electro-Optical Characteristics (Ta=25°C)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
Luminous Intensity	I _v	112	-----	285	mcd	I _F =10mA
Viewing Angle	2θ 1/2	-----	130	-----	deg	
Forward Voltage	V _F	2.70	-----	3.30	V	
Reverse Current	I _R	-----	-----	50	μA	V _R =5V

Notes:

1.Tolerance of Luminous Intensity ±10%

2.Tolerance of Forward Voltage ±0.05V

Bin Range Of Luminous Intensity & Forward Voltage

Symbol	Bin Code	Min.	Max.	Unit	Condition
I _v	R1	112	140	mcd	I _F =10mA
	R2	140	180		
	S1	180	225		
	S2	225	285		
V _F	1	2.70	2.80	V	I _F =10mA
	2	2.80	2.90		
	3	2.90	3.00		
	4	3.00	3.10		
	5	3.10	3.20		
	6	3.20	3.30		

Notes:

- 1.Tolerance of Luminous Intensity ±10%**
- 2.Tolerance of Forward Voltage ±0.05V**

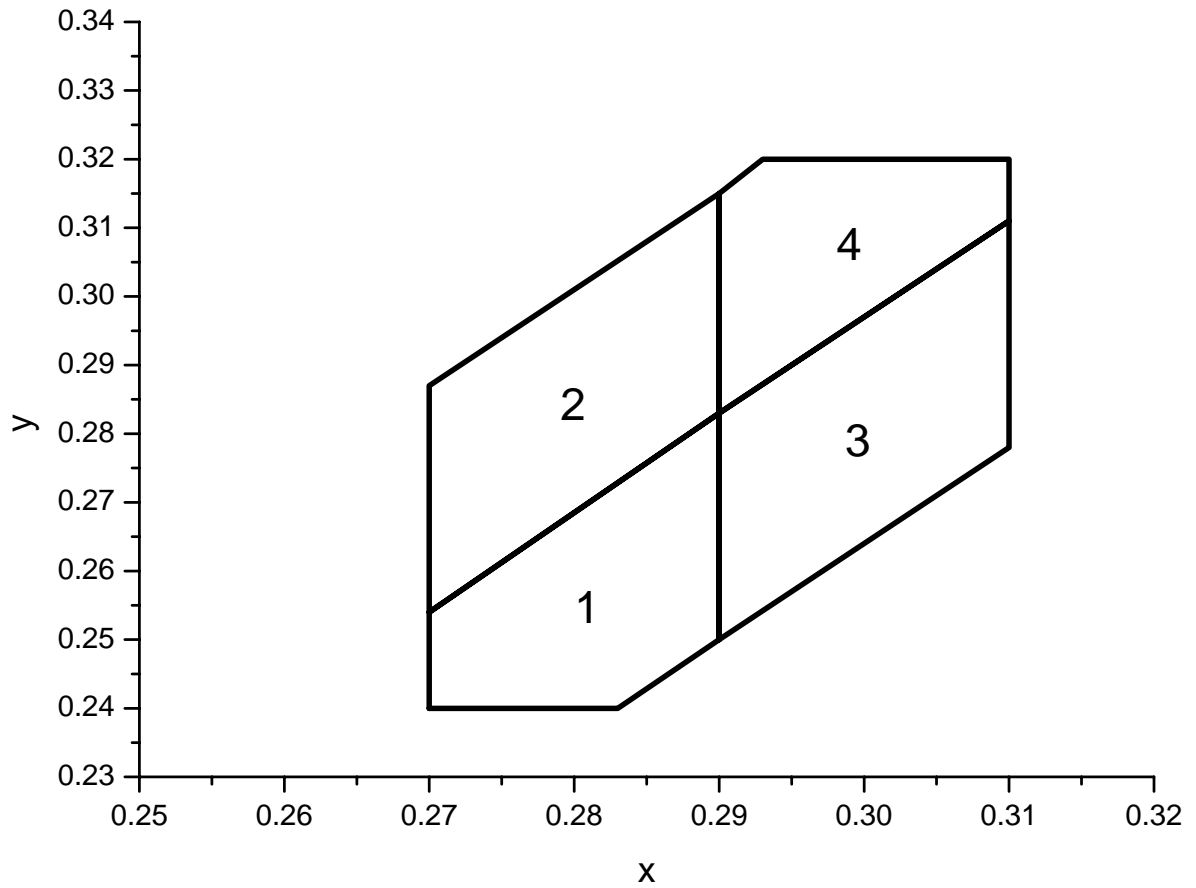
Chromaticity Coordinates Specifications for Bin Grading

Bin Code	CIE_x	CIE_y	Condition
1	0.27	0.24	IF=10mA
	0.27	0.254	
	0.29	0.283	
	0.29	0.25	
	0.283	0.24	
2	0.27	0.254	
	0.27	0.287	
	0.29	0.315	
	0.29	0.283	
3	0.29	0.25	
	0.29	0.283	
	0.31	0.311	
	0.31	0.278	
4	0.29	0.283	
	0.29	0.315	
	0.293	0.32	
	0.31	0.32	
	0.31	0.311	

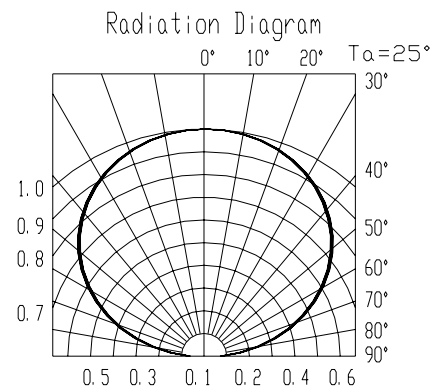
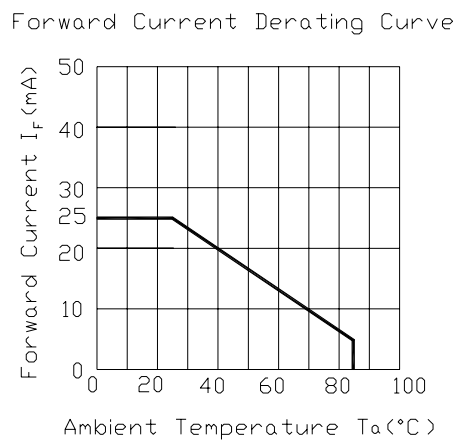
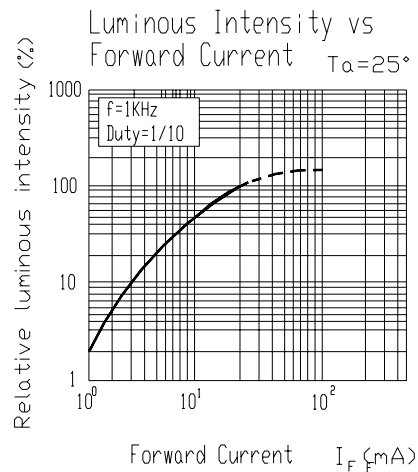
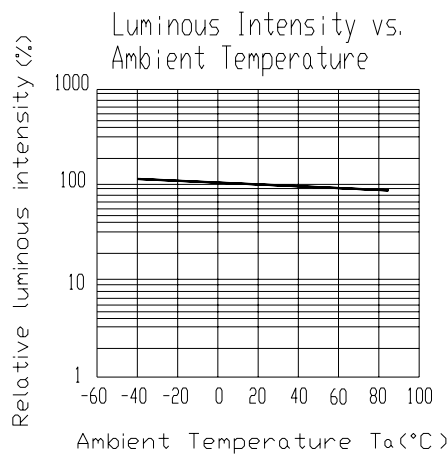
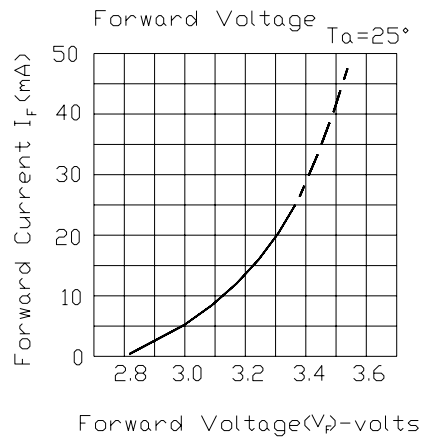
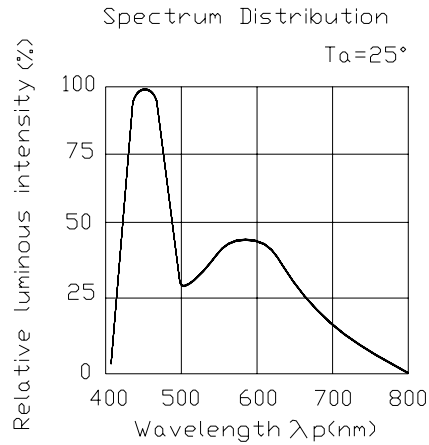
Notes:

- 1.The C.I.E. 1931 chromaticity diagram (Tolerance ± 0.01).**
- 2.The products are sensitive to static electricity and care must be fully taken when handling products.**

CIE Chromaticity Diagram

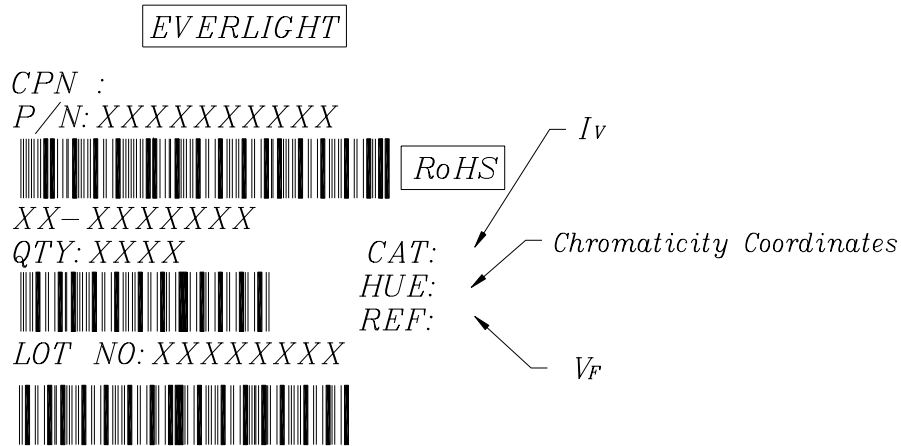


Typical Electro-Optical Characteristics Curves



Label explanation

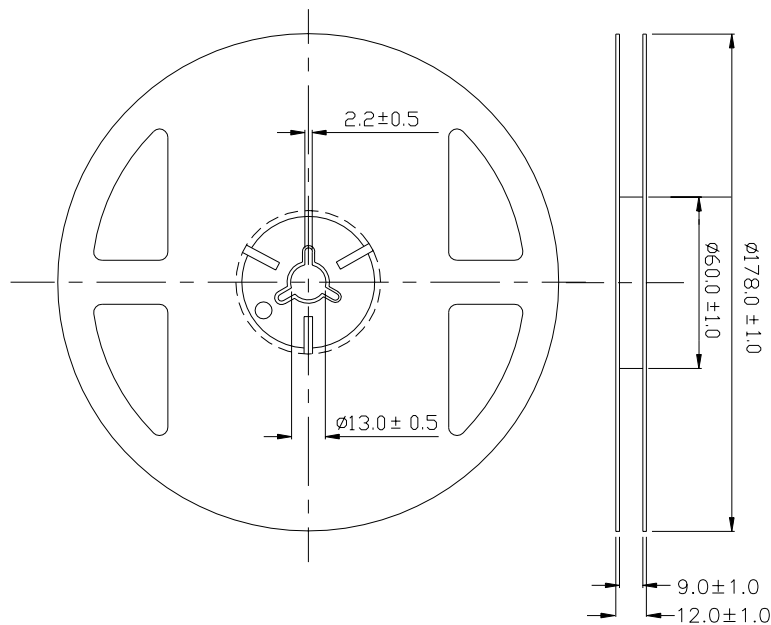
CAT: Luminous Intensity Rank HUE: Chromaticity Coordinates REF: Forward Voltage Rank



MADE IN TAIWAN

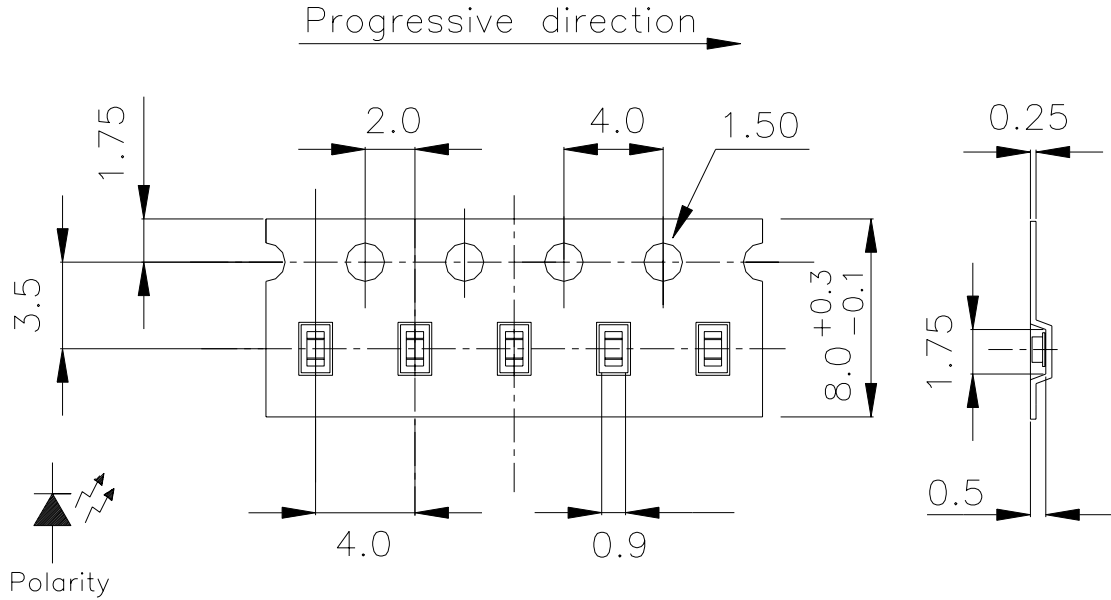
MSL-2

Reel Dimensions



Note: The tolerances unless mentioned is $\pm 0.1\text{mm}$, Unit = mm

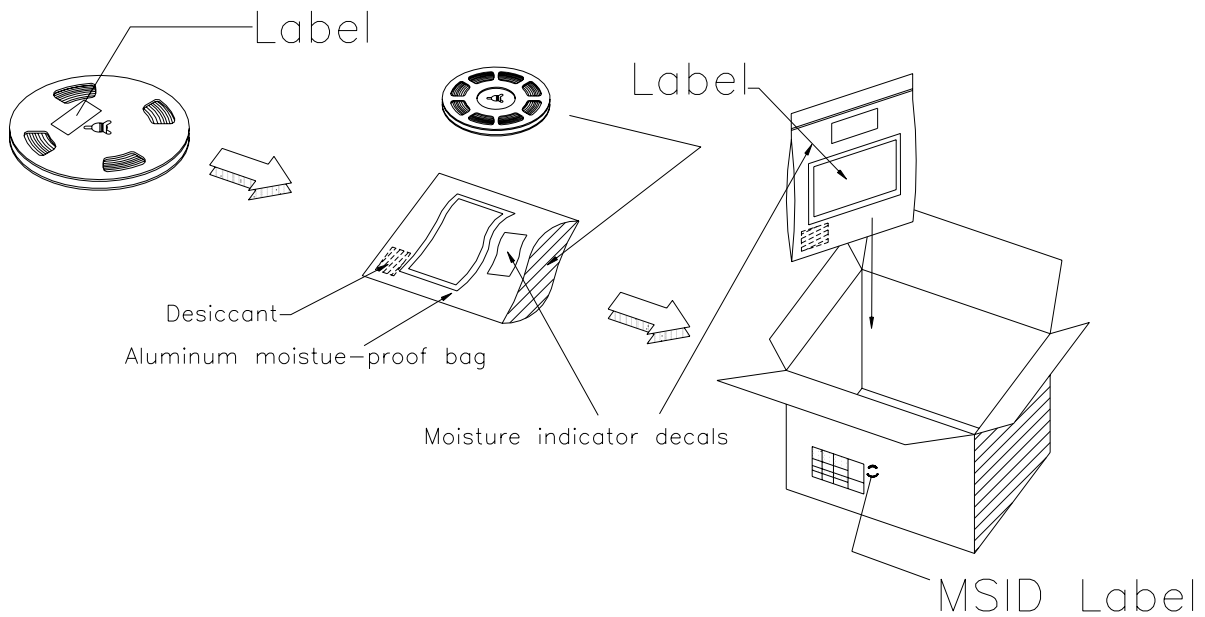
Carrier Tape Dimensions:



Quantity: 3000 PCS per reel

Note: The tolerances unless mentioned is ± 0.1 mm ,Unit = mm

Moisture Resistant Packaging



Detail of MSID label



Detail of Moisture indicator decals

	<p>CAUTION This bag contains MOISTURE SENSITIVE DEVICES</p> <ol style="list-style-type: none">1.Shelf life in sealed bag:12 months at 5°C~30°C and <90% relative Humidity(RH).2.Devices have to be mounted within 168 hours or stored at 70%RH after this bag is opened ; otherwise, the warranty of the devices will be voided immediately.3.If baking is required , devices may be baked for 24 hours at 65±5°C. <p>Note:Level and body temperature define by IPC/JEDEC J-STD-020B</p>	<p>LEVEL</p> <table border="1"><tr><td>2</td></tr></table> <p><small>If blank, see adjacent bar code label</small></p>	2
2			

Reliability Test Items And Conditions

The reliability of products shall be satisfied with items listed below.

Confidence level : 90%

LTPD : 10%

No.	Items	Test Condition	Test Hours/Cycles	Sample Size	Ac/Re
1	Reflow Soldering	Temp. : 260°C ±5°C Min. 5sec.	6 Min.	22 PCS.	0/1
2	Temperature Cycle	H : +100°C 15min ∫ 5 min L : -40°C 15min	300 Cycles	22 PCS.	0/1
3	Thermal Shock	H : +100°C 5min ∫ 10 sec L : -10°C 5min	300 Cycles	22 PCS.	0/1
4	High Temperature Storage	Temp. : 100°C	1000 Hrs.	22 PCS.	0/1
5	Low Temperature Storage	Temp. : -40°C	1000 Hrs.	22 PCS.	0/1
6	DC Operating Life	I _F = 20 mA	1000 Hrs.	22 PCS.	0/1
7	High Temperature / High Humidity	85°C / 85%RH	1000 Hrs.	22 PCS.	0/1

Judgment Criteria of Failure for Reliability Test

Measuring Item	Symbol	Measuring Condition	Judgments Criteria for Failure
Forward Voltage	V _F	I _F =10mA	>U x 1.2
Reverse Current	I _R	V _R =5V	>U x 2.0
Luminous Intensity	I _v	I _F =10mA	>S x 0.5

Note: U means the upper limit of the specified characteristics. S means the initial value.

Precautions For Use

1. Over-current-proof

Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change (Burn out will happen).

2. Storage

2.1 Do not open moisture proof bag before the products are ready to use.

2.2 Before opening the package: The LEDs should be kept at 30°C or less and 90%RH or less.

2.3 After opening the package: The LED's floor life is 1 year under 30 deg C or less and 60% RH or less.

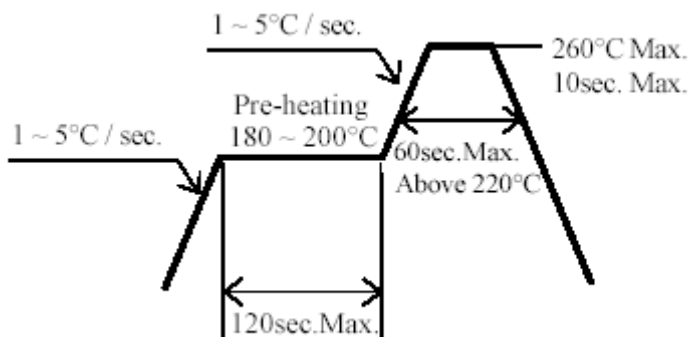
If unused LEDs remain, it should be stored in moisture proof packages.

2.4 If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions.

Baking treatment : 60±5°C for 24 hours.

3. Soldering Condition

3.1 Pb-free solder temperature profile



3.2 Reflow soldering should not be done more than two times.

3.3 When soldering, do not put stress on the LEDs during heating.

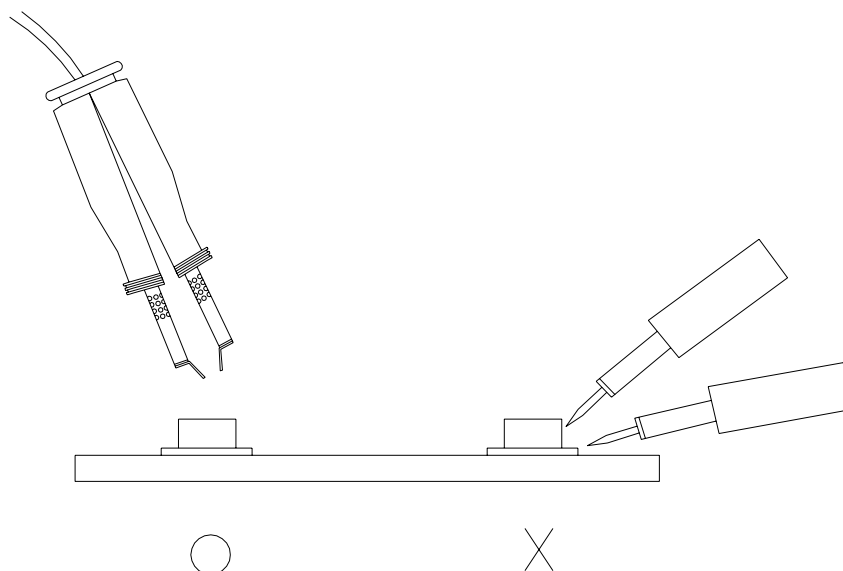
3.4 After soldering, do not warp the circuit board.

4.Soldering Iron

Each terminal is to go to the tip of soldering iron temperature less than 350°C for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

5.Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.



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